

Applicants: TAY, Cheng Siew, et al.  
Serial No.: 10/735,638  
Filed: December 16, 2003  
Page 2

RECEIVED  
CENTRAL FAX CENTER  
JUN 11 2007

### IN THE CLAIMS

Please cancel the claims marked as cancelled without prejudice.

#### Listing of Claims

1. (Cancelled)
2. (Cancelled)
3. (Cancelled)
4. (Cancelled)
5. (Cancelled)
6. (Cancelled)
7. (Cancelled)
8. (Original) A printed circuit board comprising:  
pads suitable to be soldered to respective solder-balls of a device, said pads having microvias located therein, where a center of a microvia of a pad is farther than a center of said pad from a crack initiation point located on a perimeter of said pad at a location where cracks in a solder-ball are anticipated to start after said solder-ball is soldered to said pad.
9. (Original) The printed circuit board of claim 8, wherein at least one of said pads is a metal-defined pad.
10. (Original) The printed circuit board of claim 8, wherein at least one of said pads is a solder-mask-defined pad.
11. (Original) The printed circuit board of claim 8, wherein at least one of said pads is substantially round.
12. (Original) The printed circuit board of claim 8, wherein at least one point of the perimeter of said microvia is located on the perimeter of said pad.

Applicants: TAY, Cheng Siew, et al.  
Serial No.: 10/735,638  
Filed: December 16, 2003  
Page 3

13. (Original) The printed circuit board of claim 11, wherein a straight line joining said crack initiation point and said center of said microvia is parallel to the projection onto the pad of the crack propagation direction for said solder-ball.
14. (Original) The printed circuit board of claim 13, wherein at least one point of the perimeter of said microvia is located on the perimeter of said pad.
15. (Original) A printed circuit board having a device installed thereon, the printed circuit board comprising:  
pads soldered to respective solder-balls of said device, said pads having microvias located therein, where a center of a microvia of a pad is farther than a center of said pad from a crack initiation point located on a perimeter of said pad at a location where cracks in a solder-ball are anticipated to start after said solder-ball is soldered to said pad,  
wherein said printed circuit board has a voltage monitor installed thereon.
16. (Original) The printed circuit board of claim 15, wherein at least one of said pads is a metal-defined pad.
17. (Original) The printed circuit board of claim 15, wherein said printed circuit board is a motherboard.

18-38. (Cancelled)